# Secondary Side Synchronous Flyback Controller

The NCP4302 is a full featured controller and driver that provide all the control and protection functions necessary for implementing a synchronous rectifier operation in a flyback converter. With the use of the NCP4302, the space conscious flyback applications such as Adaptors, chargers, set top boxes can achieve significant efficiency improvements at minimal extra cost. In addition to the synchronous rectifier control, the IC incorporates an accurate TL431 type shunt regulator, current monitoring circuit and optocoupler driver to provide a single IC secondary solution. The NCP4302 works with any type of flyback topology (continuous mode, Quasi–resonant mode or discontinuous mode) – providing a high level of versatility.

#### **Features**

- Self-contained Control of Synchronous Rectifier in CCM, DCM, and QR Flyback Applications
- Interface to External Signal for CCM Mode
- True Secondary Zero Current Detection
- High Gate Drive Currents (2.5 A Source/Sink)
- High Voltage Operation
- Current Sense Flexibility (MOSFET R<sub>DS(on)</sub> OR CS Resistor)
- Accurate Low Voltage Reference
  - NCP4302A 2.55 V. 1%
  - NCP4302B 1.275 V, 1%
- Programmable Independent Secondary Side ton and toff Delays
- Maximum Frequency of Operation up to 250 kHz
- These are Pb-Free Devices

# **Typical Applications**

- Notebook Adapters
- LCD TV Adapters
- Consumer Appliances such as DVD, VCR
- Power Over Ethernet Applications (IP phones, Wireless Access Points)

1

• Battery Chargers



# ON Semiconductor®

#### www.onsemi.com

# MARKING DIAGRAM



SO-8 D SUFFIX CASE 751



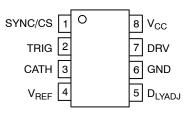
= Reference Voltage (A or B)

= Assembly Location

L = Wafer Lot
 Y = Year
 W = Work Week

= Pb-Free Package

#### **PIN CONFIGURATION**



(Top View)

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NCP4302ADR2G	SO-8 (Pb-Free)	2500/Tape & Reel
NCP4302BDR2G	SO-8 (Pb-Free)	2500/Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### **PIN DESCRIPTION**

Pin Number	Symbol	Description
1	SYNC/CS	Connected to the flyback winding. The current on this pin is sensed and used to turn on the Synchronous Rectification MOSFET (SRFET). This pin is also used to sense the zero crossing of the MOSFET current either using the $R_{DS(on)}$ of the SRFET or using an external current sense resistor connected between drain of the SRFET and the flyback winding.
2	TRIG	Input pin for direct turn-off of the MOSFET. Typically connected to a signal from primary controller (for CCM mode) or a signal derived from the transformer (for QR mode). Has very short propagation delay to output (<50 ns).
3	CATH	Feedback compensation pin for the TL431 shunt regulator. Has the capability to sinking 10 ma of opto current.
4	$V_{REF}$	Output voltage feedback through resistive divider connected to this pin. Regulated at 1.28 V (option B) or 2.55 V (option A).
5	D <sub>LYADJ</sub>	A resistive divider between the power supply output and ground with the center point tied to the $D_{LYADJ}$ input pin allows for independent adjustment of the minimum $t_{on}$ and $t_{off}$ delay time. The maximum external capacitance from this pin to ground is 25 pF.
6	GND	Return pin for the controller – connected to the output return.
7	DRV	Drive output for external MOSFET – 2.5 A peak drive capability, internally clamped to 13.5 V (Maximum)
8	V <sub>CC</sub>	Bias voltage for the controller. Maximum voltage is 28 V.

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Power Supply Input Current	V <sub>CC</sub> I <sub>CC</sub>	-0.3 to 28 100	V mA
Drive Voltage Current	V <sub>DRV</sub>	-0.3 to 18 100	V mA
Drive Current Source Sink	I <sub>DRV</sub>	2.5 -2.5	Apk
Analog and Logic Inputs	TRIG, V <sub>REF</sub> , D <sub>LYADJ</sub>	-0.3 to 10 100	V mA
Maximum Voltage Current	SYNC/CS	– 10 to 95 100	V mA
Operating Junction Temperature Range	T <sub>J</sub>	-40 to 125	°C
Maximum Junction Temperature	T <sub>Jmax</sub>	150	°C
Storage Temperature Range	T <sub>Smax</sub>	-65 to 150	°C
Lead Temperature (Soldering, 10 s)	T <sub>Lmax</sub>	300	°C
Reference input Current, continuous	I <sub>REF</sub>	-0.05 to 10	mA
Total Power Dissipation	P <sub>D</sub>	225	mW
Thermal Resistance Junction-to-Ambient	$\theta_{JA}$	178	°C/W

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

This device series contains ESD protection and exceeds the following tests:
 Pin 1–8: Human Body Model 2000 V per JEDEC Standard JESD22, Method A114E.
 Machine Model (MM) 200 V per JEDEC Standard JESD22, Method A115A.

 This device contains Latch-up protection and exceeds ±100 ma per JEDEC Standard JESD78

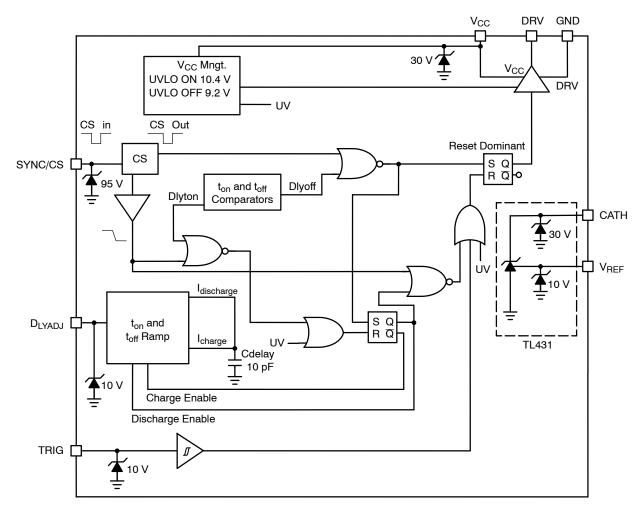


Figure 1. Block Diagram

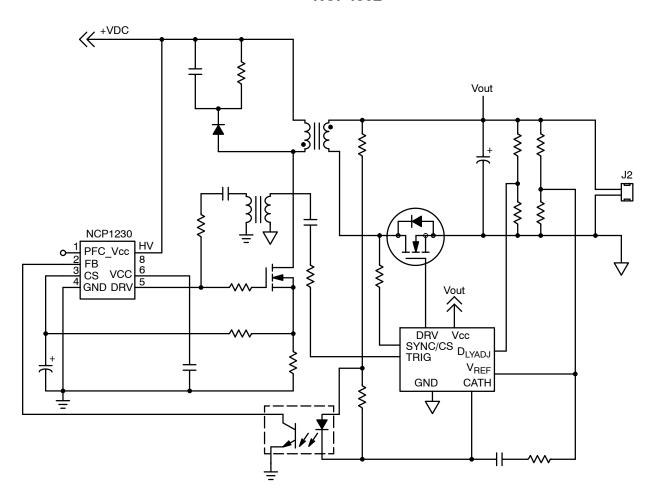


Figure 2. Typical Application

# **ELECTRICAL CHARACTERISTICS**

 $(V_{CC}=19~V,~Sync~frequency=100~kHz,~V_{REF}=V_{KA}~(I_{KA}=1~mA),~R_S=75~ohms,~V_{TRIG}=GND,~C_{DRV}=1~nF,~R_{DLYADJ}=30.1~k,\\V_{DLYADJ}=2.0~V,~for~typical~values~T_J=25^{\circ}C,~for~min/max~values~T_J=-40^{\circ}C~to~+125^{\circ}C,~Max~T_J=150^{\circ}C,~unless~otherwise~noted)$ 

Rating	Test Conditions	Symbol	Min	Тур	Max	Unit
V <sub>CC</sub>		•				
Start–up Threshold $V_{CC}$ ↑, SYNC/CS = 0 to $-0.5$ V $100$ kHz, 5 $\mu s$ pulse, Trig = 0 V		V <sub>CC(on)</sub>	9.6	10.4	11.2	V
Stop Threshold	$V_{CC} \downarrow$ , SYNC/CS = 0 to -0.5 V 100 kHz, 5 μs pulse, Trig = 0 V	V <sub>CC(off)</sub>	8.5	9.2	_	٧
V <sub>CC</sub> shutdown Hysteresis	$V_{CC(on)} - V_{CC(off)}$	V <sub>CC(HYS)</sub>	0.9	1.2	1.4	V
Supply current after turn-on	no–load on DRV pin, SYNC/CS = 0 to –0.5 V 100 kHz, 5 $\mu$ s pulse, Trig = 0 V	I <sub>CC1</sub>	-	2.7	5.6	mA
Supply current after turn-on	SYNC/CS = 0 to $-0.5$ V 100 kHz, 5 $\mu$ s pulse, Trig = 0 V	I <sub>CC2</sub>	ı	3.6	7.5	mA
DRIVE OUTPUT						
Output voltage rise-time	10–90% of the output signal SYNC/ CS = 0 to –0.5 V 100 kHz, 5 $\mu$ s pulse, Trig = 0 V	t <sub>r</sub>	-	-	40	ns
Output voltage fall-time	10–90% of the output signal SYNC/ CS = 0 to –0.5 V, 100 kHz, 5 $\mu$ s pulse, Trig = 0 V	t <sub>f</sub>	-	-	40	ns
Output source current (Note 3)		I <sub>DRV(source)</sub>	-	2.5	_	Apk
Driver high level output voltage	e I <sub>SOURCE</sub> = 200 mA, SYNC/CS = 0 to -0.5 V 100 kHz, 5 μs pulse, Trig = 0 V, V <sub>CC</sub> = 12 V		6.5	9.5	_	V
Output sink current (Note 3)		I <sub>DRV(sink)</sub>	-	2.5	_	Apk
Driver Output low level output voltage	$I_{SINK}$ = 200 mA, SYNC/CS = 0 to -0.5 V 100 kHz, 5 μs pulse, Trig = 0 V, V <sub>CC</sub> = 12 V	V <sub>DRV(L)</sub>	-	160	500	mV
Drive voltage internal clamp	$V_{CC}$ = 28 V, SYNC/CS = 0 to -0.5 V 100 kHz, 5 μs pulse, Trig = 0 V, DRVpin = 10 kΩ	V <sub>DRV(CLMP)</sub>	-	-	17	V
Minimum drive output voltage	$\begin{array}{c} V_{CC} = V_{CC(off)} + 200 \text{ mV, DRV pin =} \\ 10 \text{ k}\Omega + 1 \text{ nF, SYNC/CS = 0 to } -0.5 \text{ V} \\ 100 \text{ kHz, 5 } \mu \text{s pulse, Trig = 0 V} \end{array}$	V <sub>DRV(MIN)</sub>	5.5	6.5	-	V
SYNC/CS		ı			1	
The total propagation delay from SYNC/CS to the DRV output	SYNC/CS = $+0.5$ V to $-0.5$ V 100 kHz, 5 $\mu$ s pulse, (Trig = 0 V)(Refer to the Drive Output specifications for Tr 50% of the output signal	t <sub>p1</sub>	-	70	135	ns
Zero Current Detection	V <sub>SYNC/CS</sub> < -30 mV	Is(zcd)	50	230	450	μА
Current Sense Pin Offset Voltage at Zero Current Level (Note 3)		VS(ZCD)	-30	-	-	mV
SYNC/CS Leakage current	V <sub>SYNC/CS</sub> = 95 V	SCS <sub>Leakage</sub>	-	-	10	μΑ
TRIGGER SECTION						
Minimum Trigger pulse duration	SYNC/CS = 0 to $-0.5$ V 100 kHz, 5 $\mu$ s pulse, Trig $\uparrow$	trig-pw	75	-	_	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Guaranteed by Design

# **ELECTRICAL CHARACTERISTICS**

 $(V_{CC}=19~V,~Sync~frequency=100~kHz,~V_{REF}=V_{KA}~(I_{KA}=1~mA),~R_S=75~ohms,~V_{TRIG}=GND,~C_{DRV}=1~nF,~R_{DLYADJ}=30.1~k,\\V_{DLYADJ}=2.0~V,~for~typical~values~T_J=25^{\circ}C,~for~min/max~values~T_J=-40^{\circ}C~to~+125^{\circ}C,~Max~T_J=150^{\circ}C,~unless~otherwise~noted)$ 

Rating	Test Conditions	Symbol	Min	Тур	Max	Unit
TRIGGER SECTION		•		•	•	•
Trigger Pulse Voltage for Gate turn-off	SYNC/CS = 0 to $-0.5$ V 100 kHz, 5 $\mu$ s pulse, Trig $\uparrow$	Vtrig	2.0	_	4.0	V
Propagation delay from TRIG to DRV turn-off	C <sub>DRV</sub> = no-load, SYNC/CS= -0.5 V 100 kHz, 5 μs pulse, Trig = 0-5 V ↑	t <sub>p2</sub>	-	25	85	ns
TL431 CHARACTERISTICS						
Reference input voltage	I <sub>KA</sub> = 5 mA, V <sub>KA</sub> = V <sub>REF</sub> NCP4302A	V <sub>REF</sub>				٧
	$T_J = +25^{\circ}C$ $T_J = -40^{\circ}C$ to +125°C		2.525 2.499	2.55 –	2.575 2.60	
Reference input voltage	$(I_K = 5 \text{ mA}, V_{KA} = V_{REF})$ NCP4302B $T_J = +25^{\circ}C$ $T_J = -40^{\circ}C$ to +125°C	V <sub>REF</sub>	1.262 1.249	1.275 -	1.288 1.301	V
Reference Input Current	I <sub>KA</sub> = 10 mA	I <sub>Ref</sub>	_	0.0018	4.0	μΑ
Minimum CATH current for regulation	I <sub>SOURCE</sub> ↑ 0 to 1 mA	I <sub>KA</sub>	-	0.5	1.0	mA
Reference voltage line regulation	$\Delta V_{KA} = V_{CCon} - 16 \text{ V}, I_{KA} = 1 \text{ mA}$ $= \frac{\Delta V_{REF}}{\Delta V_{KA}}$	V <sub>KA</sub>	_	2.0	5.0	mV/V
Off-State CATH Current	V <sub>KA</sub> = 18 V, V <sub>REF</sub> = 0 V (test circuit 2, V <sub>REF</sub> pin grounded)	I <sub>Off</sub>	-	11	20	μΑ
Dynamic impedance	$V_{KA} = V_{REF}$ , $\Delta I_{KA} = 1$ mA to 10 mA	Z <sub>KA</sub>	-	0.62	1.5	Ω
The maximum sink current capability	(I <sub>SOURCE</sub> ↑ 0 to 10 mA)	Isinkmax	10	-	_	mA
ADJUSTABLE TIME DELAY				•	•	•
The t <sub>on</sub> time delay	SYNC/CS = 0 to $-0.5$ V 100 kHz, 5 $\mu$ s pulse, Trig = 0 V CD <sub>LYADJ</sub> internal = 10 pF (Vs = 2.0 V, Rth = 30.1 $\mu$ C)	<sup>t</sup> on(delay)	1.0	1.4	1.8	μs
The min and max t <sub>on(delay)</sub> range (Note 3)	* R2 = 190 kΩ, R3 = 57 kΩ * R2 = 499 kΩ, R3 = 39 kΩ (*See Figure 27)	t <sub>on(range)</sub>	0.45 -	_ _	_ 2.0	μs
The maximum and minimum input voltage operating range. (Note 3)	The maximum capacitance from pin 5 to ground is 25 pF.	Vin <sub>DLYADJ</sub>	1.5	-	4.5	V
The maximum and minimum input operating current into the D <sub>LYADJ</sub> pin (Note 3)		lin <sub>DLYADJ</sub>	9	_	200	μΑ
The t <sub>off</sub> time delay	SYNC/CS = 0 to $-0.5$ V 100 kHz, 5 $\mu$ s pulse, Trig = 0 V CD <sub>LYADJ</sub> internal = 10 pF (Vs = 2.0 V, Rth = 30.1 k)	t <sub>off(delay)</sub>	2.8	3.8	4.8	μs
The min and max t <sub>off(delay)</sub> range (Note 3)	R2 = 66 k, R3 = 23.6 k * R2 = 408 k, R3 = 32.4 k (*See the schematic below)	t <sub>off(range)</sub>	0.8	- -	- 4.6	μs

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Guaranteed by Design

### **TYPICAL CHARACTERISTICS**

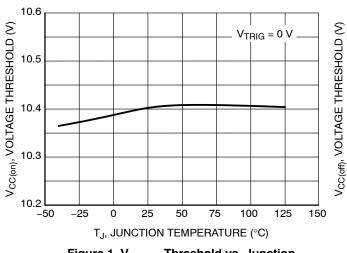


Figure 1. V<sub>CC(on)</sub> Threshold vs. Junction Temperature

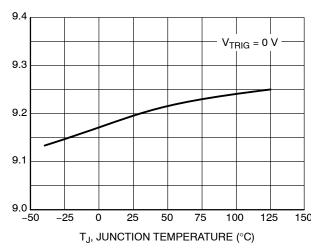


Figure 2. V<sub>CC(off)</sub> vs. Junction Temperature

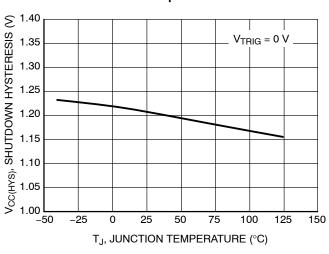


Figure 3. V<sub>CC(HYS)</sub> vs. Junction Temperature

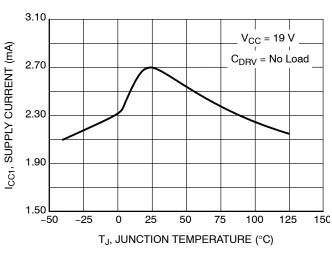


Figure 4. Internal Current Consumption at No Load vs. Junction Temperature

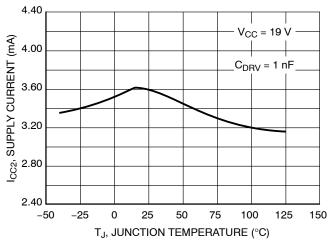


Figure 5. Supply Current Consumption with 1 nF Load vs. Junction Temperature

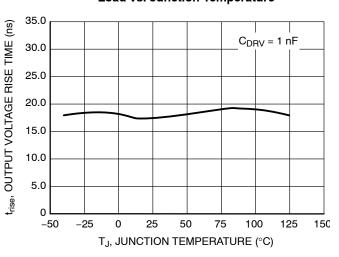
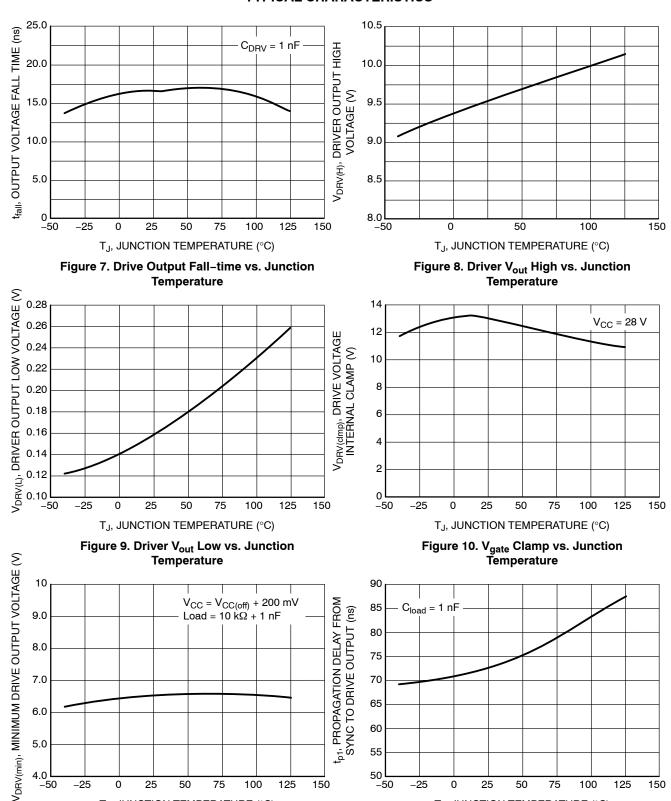


Figure 6. Drive Output Rise Time vs. Junction Temperature

### TYPICAL CHARACTERISTICS



T<sub>J</sub>, JUNCTION TEMPERATURE (°C) Figure 11. V<sub>OUT(min)</sub> vs. Junction Temperature

50

100

125

150

-50

-25

Figure 12. t<sub>p1</sub> Propagation Delay, SYNC/CS to DRIVE vs. Junction Temperature

50

T<sub>J</sub>, JUNCTION TEMPERATURE (°C)

75

100

125

25

-50

-25

#### TYPICAL CHARACTERISTICS

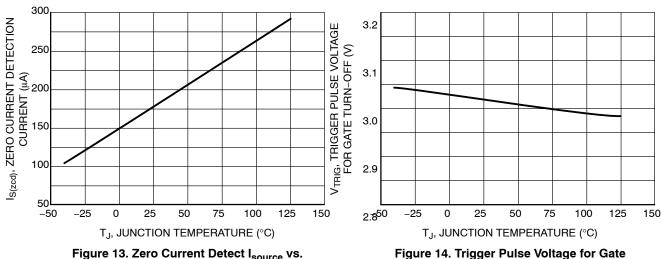
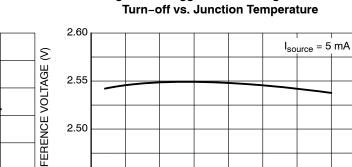


Figure 13. Zero Current Detect I<sub>source</sub> vs. Junction Temperature



2.45

2.40

-50

-25

90 t<sub>p2</sub>, PROPAGATION DELAY FROM TRIG TO DRV TURN-OFF(ns) V<sub>REF</sub>, REFERENCE VOLTAGE (V) 70 60 50 40 30 20I -50 -25 50 75 100 125 150 T<sub>J</sub>, JUNCTION TEMPERATURE (°C)

Figure 15.  $t_{\rm p2}$  Propagation Delay TRIG in to DRIVE Off, NO Load vs. Junction Temperature

T<sub>J</sub>, JUNCTION TEMPERATURE (°C)

Figure 16. 2.55 V Reference (Option A) Voltage
vs. Junction Temperature

50

75

100

125

150

25

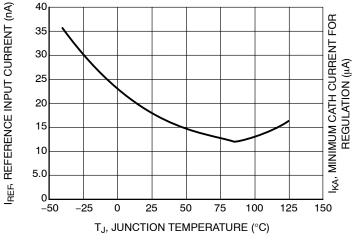


Figure 17. 2.55 V Reference Input Current vs.
Junction Temperature

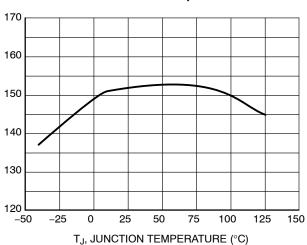


Figure 18. 2.55 V Reference Minimum Cathode Current for Regulation vs. Junction Temperature

#### **TYPICAL CHARACTERISTICS**

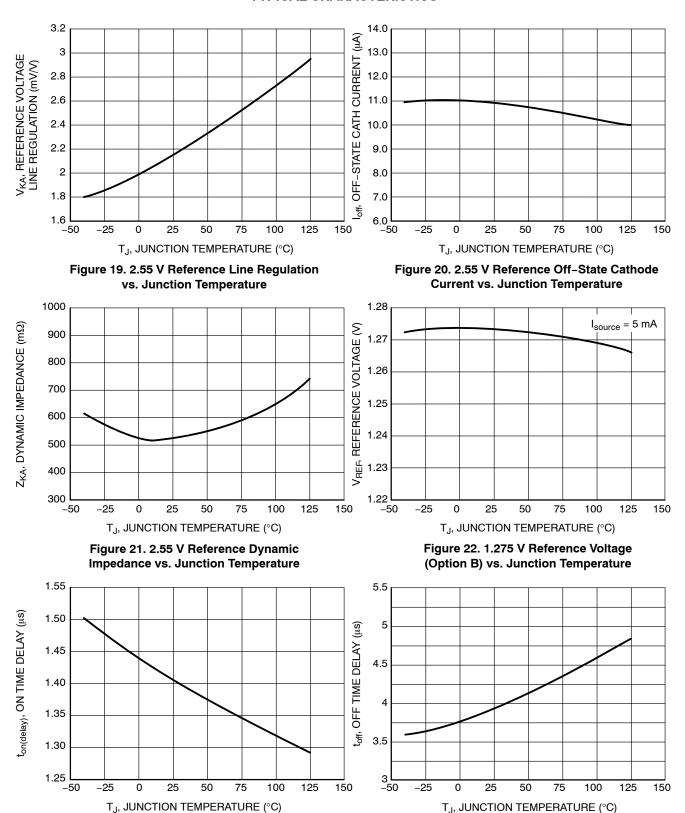


Figure 23. t<sub>on</sub> Delay vs. Junction Temperature

Figure 24. t<sub>off</sub> Delay vs. Junction Temperature

#### **Detailed Operating Description**

The NCP4302 is designed to operate either as a standalone IC or as a companion IC to a primary side controller to help achieve efficient synchronous rectification for flyback converter systems. It has high current gate driver along with fast logic circuitry to provide appropriately timed drive signals to a synchronous MOSFET used for output rectification in a flyback converter. With its novel architecture, the NCP4302 has enough versatility to increase the synchronous rectification efficiency under any operating mode without requiring too much complexity.

### **Supply Section**

The NCP4302 works from an available bias supply that can range from 10.4 V to 28 V (typical). This allows direct connection to the output voltage of many adapters such as notebook and LCD TV adapters. As a result, the NCP4302 simplifies circuit operation compared to other devices which require specific bias power supplies (e.g. 5 V). The high voltage capability of the  $V_{\rm CC}$  is also a unique feature designed to allow operation across a broader range of applications. To prevent gate signal from operating under inadequate bias conditions, the NCP4302 features a UVLO circuit that turns on at 10.4 V ( $V_{\rm CC}$  rising) typical and turns off at 9.2 V typical ( $V_{\rm CC}$  falling).

#### **Gate Drive Section**

The NCP4302 features high current gate drivers delivering up to (>2.5 A peak) to achieve fast turn-on and turn-off requirements in a synchronous rectifier. Having a high gate drive current enables fast turn-on when SYNC/CS signal is received (to minimize body diode conduction at the peak of the current waveform) and fast turn-off when zero current or a TRIG signals are received (to prevent current reversal or cross conduction). The higher sink current also allows the MOSFET to be kept off during the instances when there is high dv/dt on the drain.

The gate voltage is clamped at 13.5 V typical to prevent larger excursion of gate voltage than needed when  $V_{\rm CC}$  is operating from a 28 Vdc output.

The propagation delays through the logic circuits and the gate drivers are kept at a minimum as shown in the specification table.

#### SYNC/CS Input

In a synchronous rectification application after the primary side MOSFET is turned-off, the current in the secondary of the flyback transformer initially flows through the synchronous rectification MOSFET's internal body diode. When this occurs, the drain of the MOSFET will be -0.5 to -1.0 V negative with respect to ground (the VF of the internal body diode) and the NCP4302 current sense differential amplifier will output a 230  $\mu$ A current (typical). This current detection method is used by the NCP4302 to determine when current is flowing in the secondary of the transformer and the Synchronous Rectification MOSFET needs to be turned-on.

The zero current detection senses the current with a slight negative offset so that the switch turn-off occurs without reversal of the current.

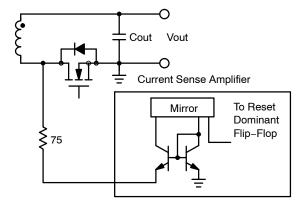


Figure 25. Input Current Sense

#### Adjustable ton Delay

The SYNC/CS input to the NCP4302 is used as a Reset (through logic) input to the drive enable Flip Flop; refer to the internal block diagram of the NCP4302. When current flows in the secondary of the Flyback transformer any parasitic inductance due to printed wiring board traces, or component lead can cause the voltage at the SYNC/CS input to ring above ground (refer to Figure 26). This ringing may cause the controller dive output to turn–off. To eliminate this problem the NCP4302 has a programmable t<sub>on</sub> time which blanks the secondary voltage ringing by adding a minimum controller drive on time.

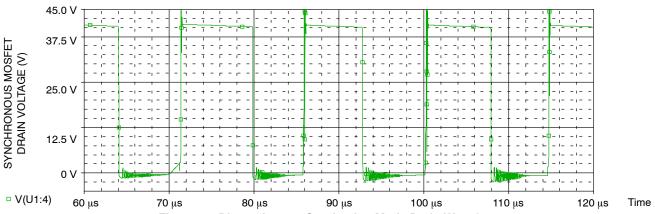


Figure 26. Discontinuous Conduction Mode Drain Waveform

The minimum on time is set with a voltage divider with resistors R2 and R3 (refer to Figure 27).

$$I_{in} = \left( \left( V_{out} \cdot \frac{R3}{R3 + R2} \right) - \ 0.7 \right) \cdot \frac{1}{Rth}$$

Where Rth is the Thevenin equivalent resistance and is calculated by:

$$Rth = \frac{1}{\frac{1}{R3} + \frac{1}{R2}}$$

This input current is then used to charge an internal 10~pF capacitor setting the minimum  $t_{on}$  time.

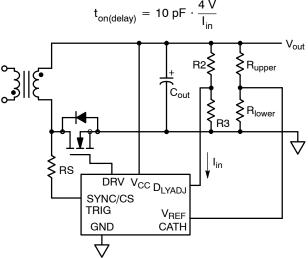


Figure 27. Typical Application

#### Adjustable toff Delay

The SYNC/CS input to the NCP4302 is used as the Set input to the drive enable Flip Flop; refer to the internal block diagram of the NCP4302. Refering to the SPICE simulations (Figure 28), you can see that when the system is operating under light load conditions the transformer secondary voltage rings below ground when the current reaches zero. When this occurs, the CS amplifier output may be falsely triggered providing a Set input to the Drive Flip Flop, turning on the output drive. To prevent the controller from prematurely turning on the synchronous rectification MOSFET, the output of the current sense amplifier is connected to a logic block with a programmable off time delay. The  $t_{\rm off(delay)}$  can be independently programmed through the  $D_{\rm LYADJ}$  pin.

$$\begin{split} I_{in} &= \left( \left( V_{out} \cdot \frac{R3}{R3 + R2} \right) - 0.7 \right) \cdot \frac{1}{100k} \\ &t_{off(delay)} = 10 \text{ pF} \cdot \frac{3.35 \text{ V}}{I_{in}} \end{split}$$

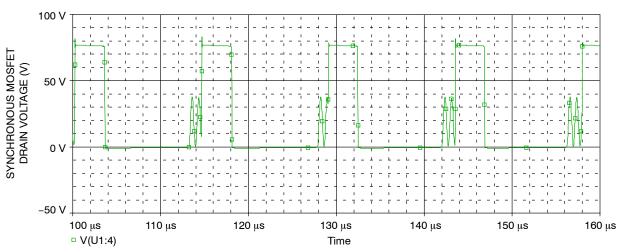


Figure 28. Discontinuous Conduction Mode Drain Waveform

#### **Trigger Input**

The TRIG input is used to turn-off the synchronous MOSFET prior to its current reaching zero. This input is required in a CCM operating mode. While there are several ways to determine the TRIG input, the simplest way is to generate a pulse in the primary side that precedes the turn-on of the primary MOSFET and transformer couple that pulse to the secondary into the Trig input. In converters where the operating mode is always designed to be DCM or QRM, the

TRIG input is not used. It is recommended to ground the TRIG pin in these cases.

#### **Voltage Amplifier and Reference**

The NCP4302 incorporates an accurate TL431 type Shunt regulator with two reference voltage options. The NCP4302A has a 2.5 V reference and the NCP4302B has a 1.25 V reference.

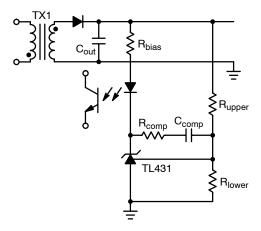


Figure 29. Typical Secondary Side Regulator

When the TL431 is being used to regulate the output of a power supply it is typically configured as shown in Figure 29. Where the output from the power supply is sensed and divided down with a resistive divider made up of  $R_{upper}$  and  $R_{lower}$ . The center point of the divider is connected to the reference pin of the NCP4302. The divider ratio scales down the output voltage to match the reference voltage, 2.5 V or 1.25 V.

$$V_{REF} = V_{out} \cdot \frac{R_{lower}}{R_{lower} + R_{upper}}$$

The R<sub>bias</sub> resistor in Figure 29 sets the current through the TL431, which must be greater than 0.5 mA to guarantee its performance under all operating conditions.

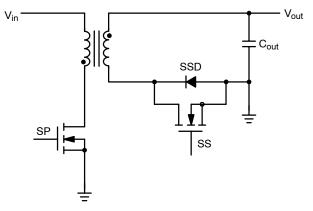


Figure 30. Synchronous Rectifier

# **Using Synchronous Rectification**

For a flyback converter to operate correctly with synchronous rectification there must be a delay between the time when the primary side MOSFET (SP Figure 30) and the secondary side Synchronous rectification MOSFETs (SS Figure 29) are conducting current. The NCP4302 can

operate in CCM, CRM, or QR modes. The next sections cover the losses associated for each of the three operating modes.

#### **Discontinuous Conduction Mode**

The basic switching waveforms for the Flyback converter operating in DCM are shown in Figure 31. When the primary side MOSFET (SP in Figure 30) is turned-on current flows is the transformer primary and ramps up from zero to Ipeak. When the primary side MOSFET (SP) turns-off, the polarity of the transformer reverses and the energy stored in the transformer is transferred to the secondary. When the energy transfer from the transformer primary to the transformer secondary begins, (prior to the secondary side synchronous MOSFET turning-on) the secondary current flows through the internal body diode synchronous rectifiers MOSFETs (SS) and (SSD). To minimize the losses in the SSD, the propagation delay (t<sub>p1</sub>) must be low. Otherwise, there will be high losses associated with the secondary peak current and the SSD forward voltage drop (NCP4302 has a typical propagation delay of 50 ns).

$$P_{Tsecondary} = P_{on} + P_{SW} + P_{diode}$$
 (eq. 1)

$$I_{out} = \frac{I_{sec,pk}}{2} \cdot (1 - D_{on})$$
 (eq. 2)

$$I_{\text{sec,rms}} = I_{\text{sec,pk}} \cdot \sqrt{\frac{1 - D_{\text{on}}}{3}}$$
 (eq. 3)

Combining equations 2 and 3,

$$I_{\text{sec,rms}}^2 = \frac{4 \cdot I_{\text{out}}^2}{3 \cdot (1 - D_{\text{on}})}$$
 (eq. 4)

$$P_{on} = \frac{4 \cdot I_{out}^2}{3 \cdot (1 - D_{on})} \cdot R_{DS(on)}$$
 (eq. 5)

$$P_{SW} = \frac{1}{2} \cdot C_{OSS} \cdot V_S^2 \cdot f \qquad (eq. 6)$$

$$P_{diode} = V_F \cdot I_{out} \cdot t_{delay}$$
 (eq. 7)

Where:

Iout is the dc output current

V<sub>F</sub> is

D is the duty cycle

R<sub>DS(on)</sub> is the on resistance of the MOSFET

$$V_S = \frac{V_{in}}{n} + V_{out}$$

n is the transformer turns ratio

T<sub>delay</sub> is the delay from the sync to the drive output

#### **Discontinuous Condition Mode**

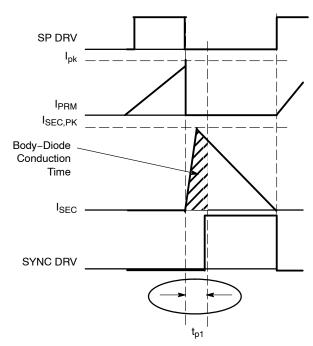


Figure 31. Discontinuous Conduction Mode Waveforms

 $t_{p1}$  is the propagation delay from the SYNC/CS input to the drive output.

#### **Continuous Conduction Mode**

When operating in continuous conduction mode (CCM) the current in the secondary doesn't fall to zero prior to turning on the primary side MOSFET. To eliminate cross conduction losses (have the primary side MOSFET and secondary side MOSFET on at the same time) the trigger input to the NCP4302 must be utilized. A signal which leads the Primary Side (SP) MOSFET turning on must be coupled to the TRIG input of the NCP4302 which will turn-off the SS MOSFET referring to Figure 32.

When the energy transfer begins in the transformer secondary, prior to the secondary side synchronous MOSFET turning—on, the secondary current flows through the synchronous rectifiers MOSFET's (SS) internal body diode (SSD). To minimize the power loss in the internal body the controller propagation delay has been minimized in the NCP4302.

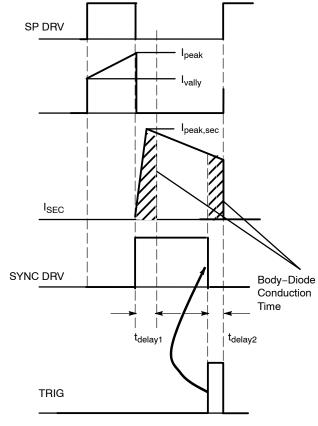


Figure 32. Continuous Conduction Mode Waveforms

$$P_{sync} = P_{ON} + P_{Qrr} + P_{d}P + PP_{OFF}$$
 (eq. 8)

$$I_{\text{sec,RMS}} \approx \left(I_{\text{sec,peak}} - \frac{\Delta I_{L_{\text{sec}}}}{2}\right)\sqrt{1 - D}$$
 (eq. 9)  
 $I_{\text{sec,RMS}}^2 \approx \left(I_{\text{sec,peak}} - \frac{\Delta I_{L_{\text{sec}}}}{2}\right)^2 1 - D$  (eq. 10)

Combining equations 9 and 10,

$$\Delta IL_{sec} = \frac{V_{OUT} + V_f}{\frac{LM}{2}} (1 - D)T \qquad (eq. 11)$$

$$P_{on} = I_{sec,RMS}^{2} \cdot R_{DS(on)}$$
 (eq. 12)

$$P_{QRR} = Q_{RR} \left( V_{OUT} + \frac{V_{IN}}{n} \right) f \qquad (eq. 13)$$

$$\mathsf{P}_{\mathsf{BODY\_DIODE}} = \mathsf{V}_f \cdot \mathsf{I}_{\mathsf{OUT}} \cdot f(\mathsf{t}_{\mathsf{delay1}} + \mathsf{td}_{\mathsf{delay2}}) \quad \text{ (eq. 14)}$$

$$P_{\text{off}} = \frac{1}{2} \cdot C_{\text{OSS}} \left( V_{\text{out}} + \frac{V_{\text{in}}}{n} \right)^2 \cdot f$$
 (eq. 15)

 $Q_{RR}$  is the recovery charge of the internal body diode Coss is the MOSFET drain to source capacitance  $L_{M}$  is the transformer primary inductance

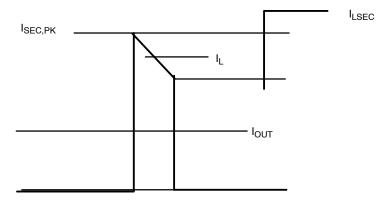


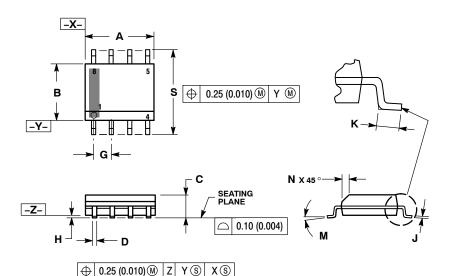
Figure 33.





SOIC-8 NB CASE 751-07 **ISSUE AK** 

**DATE 16 FEB 2011** 



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER
- ANSI Y14.5M, 1982.
  CONTROLLING DIMENSION: MILLIMETER.
- DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
- MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE
- DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
- 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	4.80	5.00	0.189	0.197
В	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
Н	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0 °	8 °	0 °	8 °
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

XXXXXX

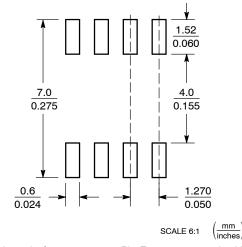
AYWW

Discrete

Ŧ  $\mathbb{H}$  AYWW

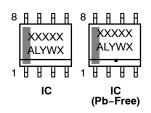
**Discrete** (Pb-Free)

# **SOLDERING FOOTPRINT\***



<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

### **GENERIC MARKING DIAGRAM\***



XXXXX = Specific Device Code = Assembly Location = Wafer Lot = Year W

XXXXXX = Specific Device Code = Assembly Location Α = Year ww = Work Week = Work Week = Pb-Free Package = Pb-Free Package

> \*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

### **STYLES ON PAGE 2**

DOCUMENT NUMBER:	98ASB42564B	Electronic versions are uncontrolled except when accessed directly from the Document Repos Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.			
DESCRIPTION:	SOIC-8 NB		PAGE 1 OF 2		

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. **onsemi** does not convey any license under its patent rights nor the rights of others.

# SOIC-8 NB CASE 751-07 ISSUE AK

# **DATE 16 FEB 2011**

			D/ (I E TO I ED E
STYLE 1: PIN 1. EMITTER 2. COLLECTOR 3. COLLECTOR 4. EMITTER 5. EMITTER 6. BASE 7. BASE 8. EMITTER	STYLE 2: PIN 1. COLLECTOR, DIE, #1 2. COLLECTOR, #1 3. COLLECTOR, #2 4. COLLECTOR, #2 6. EMITTER, #2 7. BASE, #1 8. EMITTER, #1 STYLE 6:	STYLE 3: PIN 1. DRAIN, DIE #1 2. DRAIN, #1 3. DRAIN, #2 4. DRAIN, #2 5. GATE, #2 6. SOURCE, #2 7. GATE, #1 8. SOURCE, #1 STYLE 7:	
PIN 1. DRAIN 2. DRAIN 3. DRAIN 4. DRAIN 5. GATE 6. GATE 7. SOURCE 8. SOURCE	PIN 1. SOURCE 2. DRAIN 3. DRAIN 4. SOURCE 5. SOURCE 6. GATE 7. GATE 8. SOURCE	STYLE 7: PIN 1. INPUT 2. EXTERNAL BYPASS 3. THIRD STAGE SOURCE 4. GROUND 5. DRAIN 6. GATE 3 7. SECOND STAGE Vd 8. FIRST STAGE Vd	PIN 1. COLLECTOR, DIE #1 2. BASE, #1 3. BASE, #2 4. COLLECTOR, #2 5. COLLECTOR, #2 6. EMITTER, #2 7. EMITTER, #1 8. COLLECTOR, #1
STYLE 9: PIN 1. EMITTER, COMMON 2. COLLECTOR, DIE #1 3. COLLECTOR, DIE #2 4. EMITTER, COMMON 5. EMITTER, COMMON 6. BASE, DIE #2 7. BASE, DIE #1 8. EMITTER, COMMON	STYLE 10: PIN 1. GROUND 2. BIAS 1 3. OUTPUT 4. GROUND 5. GROUND 6. BIAS 2 7. INPUT 8. GROUND	STYLE 11: PIN 1. SOURCE 1 2. GATE 1 3. SOURCE 2 4. GATE 2 5. DRAIN 2 6. DRAIN 2 7. DRAIN 1 8. DRAIN 1	STYLE 12: PIN 1. SOURCE 2. SOURCE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN
STYLE 13: PIN 1. N.C. 2. SOURCE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN	STYLE 14: PIN 1. N-SOURCE 2. N-GATE 3. P-SOURCE 4. P-GATE 5. P-DRAIN 6. P-DRAIN 7. N-DRAIN 8. N-DRAIN	7. DHAIN 1 8. DRAIN 1 STYLE 15: PIN 1. ANODE 1 2. ANODE 1 3. ANODE 1 4. ANODE 1 5. CATHODE, COMMON 6. CATHODE, COMMON 7. CATHODE, COMMON 8. CATHODE, COMMON	STYLE 16:  PIN 1. EMITTER, DIE #1 2. BASE, DIE #1 3. EMITTER, DIE #2 4. BASE, DIE #2 5. COLLECTOR, DIE #2 6. COLLECTOR, DIE #2 7. COLLECTOR, DIE #1 8. COLLECTOR, DIE #1
STYLE 17: PIN 1. VCC 2. V2OUT 3. V1OUT 4. TXE 5. RXE 6. VEE 7. GND 8. ACC	STYLE 18: PIN 1. ANODE 2. ANODE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. CATHODE 8. CATHODE	STYLE 19: PIN 1. SOURCE 1 2. GATE 1 3. SOURCE 2 4. GATE 2 5. DRAIN 2 6. MIRROR 2 7. DRAIN 1 8. MIRROR 1	STYLE 20: PIN 1. SOURCE (N) 2. GATE (N) 3. SOURCE (P) 4. GATE (P) 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN
STYLE 21: PIN 1. CATHODE 1 2. CATHODE 2 3. CATHODE 3 4. CATHODE 4 5. CATHODE 5 6. COMMON ANODE 7. COMMON ANODE 8. CATHODE 6	STYLE 22: PIN 1. I/O LINE 1 2. COMMON CATHODE/VCC 3. COMMON CATHODE/VCC 4. I/O LINE 3 5. COMMON ANODE/GND 6. I/O LINE 4 7. I/O LINE 5 8. COMMON ANODE/GND	STYLE 23: PIN 1. LINE 1 IN 2. COMMON ANODE/GND 3. COMMON ANODE/GND 4. LINE 2 IN 5. LINE 2 OUT 6. COMMON ANODE/GND 7. COMMON ANODE/GND 8. LINE 1 OUT	STYLE 24: PIN 1. BASE 2. EMITTER 3. COLLECTOR/ANODE 4. COLLECTOR/ANODE 5. CATHODE 6. CATHODE 7. COLLECTOR/ANODE 8. COLLECTOR/ANODE
STYLE 25: PIN 1. VIN 2. N/C 3. REXT 4. GND 5. IOUT 6. IOUT 7. IOUT 8. IOUT	STYLE 26: PIN 1. GND 2. dv/dt 3. ENABLE 4. ILIMIT 5. SOURCE 6. SOURCE 7. SOURCE 8. VCC	STYLE 27: PIN 1. ILIMIT 2. OVLO 3. UVLO 4. INPUT+ 5. SOURCE 6. SOURCE 7. SOURCE 8. DRAIN	STYLE 28: PIN 1. SW_TO_GND 2. DASIC_OFF 3. DASIC_SW_DET 4. GND 5. V_MON 6. VBULK 7. VBULK 8. VIN
STYLE 29: PIN 1. BASE, DIE #1 2. EMITTER, #1 3. BASE, #2 4. EMITTER, #2 5. COLLECTOR, #2 6. COLLECTOR, #2 7. COLLECTOR, #1 8. COLLECTOR, #1	STYLE 30: PIN 1. DRAIN 1 2. DRAIN 1 3. GATE 2 4. SOURCE 2 5. SOURCE 1/DRAIN 2 6. SOURCE 1/DRAIN 2 7. SOURCE 1/DRAIN 2 8. GATE 1		

DOCUMENT NUMBER:	98ASB42564B	Printed versions are uncontrolled except when accessed directly from the Document Reposito Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	SOIC-8 NB		PAGE 2 OF 2	

onsemi and ONSEMi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

onsemi, Onsemi, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at <a href="www.onsemi.com/site/pdf/Patent-Marking.pdf">www.onsemi.com/site/pdf/Patent-Marking.pdf</a>. Onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA class 3 medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase

#### ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

 $\textbf{Technical Library:} \ \underline{www.onsemi.com/design/resources/technical-documentation}$ 

onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at www.onsemi.com/support/sales